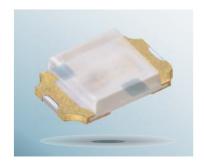


Thin Ultra-Compact PICOLED™ Chip LEDs

SML-P1 Series [15 Models]



Expanded color lineup improves design flexibility

Product Outline

ROHM is expanding its industry-leading PICOLED™ lineup of thin, ultra-compact LEDs optimized for portable devices such as smartphones and wearable tech. 7 new colors have been added to the series, increasing the number of models from 8 to 15, providing greater applicability.

Expanded 15-color lineup









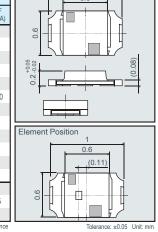








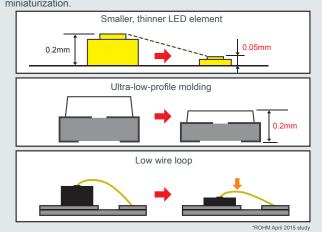
		Absolute Maximum Ratings						Electrical Characteristics										
	Part No. SML-P12VT (R) SML-P12UT (R) SML-P12UT (R) SML-P12DT (R)	Permissible	Forward Current	t IFP (mA)	Reverse Voltage VR (V)	Operating Temp. Topr (°C)	Storage Temp Tstg (°C)	Forward VF	Voltage	Forward IR	Current	Emission Wavelength ID				Luminosity'2 IV		
		Loss P _D (mW)	IF (mA)					Typ. (V)	IF (mA)	Max. (μA)	V (V)	Min.*1 (nm)	Typ. (nm)	Max.*1 (nm)	IF (mA)	Min. (mcd)	Typ.*1 (mcd)	IF (mA
	SML-P12VT (R)	50						2.0				625	630	635		25	60	
	SML-P12UT (R)	30						2.0				615	620	625		40	85	
ew	SML-P12U2T (R)											610	615	620		25	70	
L	SML-P12DT (R)											602	605	608		63	100	
ew	SML-P12Y3T (R)					-40 to	-40 to					593	596	599		40	90	
L	SML-P12YT (R)	52	20	100	5	-40 to +85	+100	2.1	20	10	5	587	590	593	20	40	100	20
ew	SML-P12WT (R)											582	585	588		25	70	
ew	SML-P12Y2T (R)											577	580	583		16	50	
ew	SML-P12M2T (R)	54						2.2				573	576	579		10	25	
L	SML-P12MT (R)	04						2.2				569	572	575		10	25	
lew	SML-P13FT (R)	52						2.1				563	566	569		6.3	18	
lew	SML-P13PT (R)	32						2.1				557	560	563		4.0	10	
	SMLP13EC8T							3.0				520	527	535		56	110	
	SMLP13BC8T	33	10	50				2.9	5	100		465	470	475	5	9.0	25	5
Г	SCMP13WBC8W							2.9				(x, y)	(0.30,	0.30)		90	150	



External Dimensions

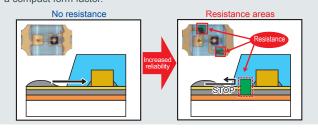
■ The industry's thinnest package* (t=0.2mm)

ROHM utilizes proprietary technologies to reduce the height of the gold wire loop and molding along with element size, resulting in breakthrough miniaturization.



High reliability package prevents solder intrusion

Solder intrusion countermeasures are implemented, taking into consideration conditions during reflow, to achieve superior reliabilty in a compact form factor.



■ Applications (Scan the 2d bar codes below to access videos)



The content specified herein is for the purpose of introducing ROHM's products (hereinafter "Products"). If you wish to use any such Product, please be sure to refer to the specifications, which can be obtained from ROHM upon request. Great care was taken in ensuring the accuracy of the information specified in this document. However, should you incur any damage arising from any inaccuracy or misprint of such information, ROHM shall bear no responsibility for such damage. The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM and other parties. ROHM shall bear no responsibility whatsoever for any dispute arising from the use of such technical information. If you intend to export or ship overseas any Product or technology specified herein that may be controlled under the Foreign Exchange and the Foreign Trade Law, you will be required to obtain a license or permit under the Law.

The content specified in this document is correct as of 2th April, 2015.

ROHM Co., Ltd. 21 Saiin Mizosaki-cho, Ukvo-ku, Kyoto 615-8585 Japan TEL:+81-75-311-2121

